



## RoHS Declaration of Conformity

This declaration covers the following products manufactured by GeneSiC Semiconductor, LLC and shipped after the date of declaration:

<b>Product Identification</b>	Refer Appendix A and Appendix B
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GeneSiC Semiconductor, LLC declares the products identified in this certificate to comply with the below stated European Union directive on restriction to the use of certain hazardous substances in electrical and electronic equipment (Appendix A and B).

### **Directive 2015/863/EU (RoHS 3)      Restriction to the Use of Hazardous Substances**

#### **Directive 2015/863/EU published on July 22<sup>nd</sup> 2019 amending Directive 2011/65/EU of the European Parliament and of the Council**

- The products are fully compliant and do not contain any of the 10 restricted substances above concentration levels noted in EU RoHS 3
- The products are compliant with EU RoHS 3 with an exempt use of one or more restricted substances

Applied Exemptions: 7a Lead – May be used in high melting temperature type solders (Lead-based alloys containing 85 % by weight or more lead)

GeneSiC Semiconductor, LLC declares the products identified in this certificate meet the **China RoHS** (China Marking for Control of Pollution Caused by Electronic Information Products Standard **SJ/T11364-2006**) (Appendix A and B).

- These Products are compliant with China RoHS using the EFUP of 25 years for lead (Pb) exceeding the 0.1% restricted level.

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<b>Date</b>	October 19 <sup>th</sup> , 2022
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 <b>GeneSiC Semiconductor, LLC</b>	
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This certification is considered to be part of GeneSiC Semiconductor's product specifications and only applies to the products' compliance with the specific regulation and industry specification listed above. Additional restrictions and/or controls relating to these or other substances and materials enacted by these or other governing bodies are outside the scope of this certification. No additional certifications, expressions of risk or liability, or further declarations are made, expressed or implied. The recipient or end user of this data is responsible for determining the applicability of this data to their specific use. GeneSiC Semiconductor reserves the right to modify or rescind this declaration with respect to products not yet defined.



## Appendix A

<b>SiC Schottky MPS™</b>
GE04MPS06E
GE04MPS06A
GE06MPS06E
GE06MPS06A
GE08MPS06E
GE08MPS06A
GE10MPS06E
GE10MPS06A
GE2X8MPS06D
GE2X10MPS06D
GD30MPS06J
GD30MPS06A
GD30MPS06H
GD2X30MPS06D
GD2X30MPS06N
GD2X100MPS06N
GD02MPS12E
GD10MPS12E
GD10MPS12A
GD10MPS12H
GD30MPS12J
GD30MPS12H
GD50MPS12H
GD2X30MPS12D
GD2X30MPS12N
GD2X50MPS12N
GD2X100MPS12N
GD05MPS17H
GD10MPS17H
GD15MPS17H
GD25MPS17H
GD60MPS17H
GD2X75MPS17N
GC05MPS33J
GC50MPS33H

<b>SiC Schottky MPS™</b>
GB01SLT06-214
GC50MPS06-247
GC2X50MPS06-227
GC2X100MPS06-227
GB01SLT12-214
GB02SLT12-214
GB01SLT12-252
GB02SLT12-252
GC02MPS12-220
GC05MPS12-252
GC08MPS12-252
GC08MPS12-220
GC2X5MPS12-247
GC10MPS12-252
GC10MPS12-220
GC15MPS12-220
GC15MPS12-247
GC2X8MPS12-247
GC20MPS12-220
GC20MPS12-247
GC2X10MPS12-247
GC2X15MPS12-247
GC2X20MPS12-247
GC50MPS12-247
GB2X50MPS12-227
GB2X100MPS12-227
GB05MPS17-263
GB05MPS17-247
GB10MPS17-247
GB25MPS17-247
GB50MPS17-247
GB2X50MPS17-227
GAP3SLT33-214
GAP3SLT33-220FP
GB05MPS33-263

<b>SiC MOSFET</b>
G3R20MT12N
G3R20MT12K
G3R30MT12K
G3R30MT12J
G3R40MT12K
G3R40MT12D
G3R40MT12J
G3R75MT12K
G3R75MT12D
G3R75MT12J
G3R160MT12D
G3R160MT12J
G3R350MT12D
G3R350MT12J
G3R20MT17N
G3R20MT17K
G3R45MT17K
G3R45MT17D
G3R160MT17D
G3R160MT17J
G3R450MT17D
G3R450MT17J
G2R1000MT17D
G2R1000MT17J
G2R50MT33K
G2R120MT33J
G2R1000MT33J
G3R60MT07K
G3R60MT07D
G3R60MT07J

## Appendix B

Silicon Products (Bridge Rectifiers, Stud Rectifiers and Rectifier Module)		
BR*	150*	FST*
DB*	1N*	MBR*
GBJ*	FR*	MBRH*
GBL*	GKN*	MBRT*
GBP*	GKR*	MSRT*
GBPC*	MBR*	MSRTA*
GBU*	MUR*	MUR*
KBJ*	S*	MURH*
KBL*	SD*	MURT*
KBP*		MURTA*
KBPC*		
KBU*		

*\* Product Series Identifier*